METHOD AND APPARATUS FOR GENERATING AN OPC SEGMENTATION BASED ON MODELLED INTENSITY GRADIENTS

ABSTRACT

One embodiment of the invention provides a system that dissects edges of a layout of an integrated circuit to produce a segmentation of the layout for a subsequent optical proximity correction (OPC) operation. In order to perform the dissection, the system first performs a model-based simulation on the layout to generate intensity gradients along edges of features in the layout. Next, the system generates a segmentation for edges in the layout based upon the intensity gradients. This segmentation is used during a subsequent optical proximity correction (OPC) process to generate corrections for the layout so that the layout prints more accurately on a semiconductor chip.